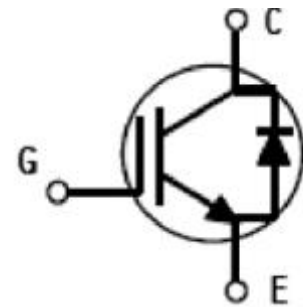


50A 1200V Trenchstop Insulated Gate Bipolar Transistor

1 Description

These Insulated Gate Bipolar Transistor used advanced trench and Fieldstop technology design, provided excellent V_{cesat} and switching speed, low gate charge. Which accords with the RoHS standard.



2 Features

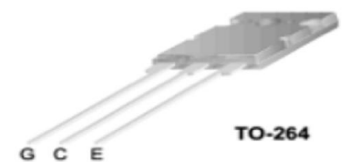
- Low V_{cesat}
- Low gate charge
- Excellent switching speed
- Easy paralleling capability due to positive

temperature Coefficient in V_{cesat}

- $T_{sc} \geq 10\mu s$
- Fast recovery full current anti-parallel diode

3 Applications

- Welding
- UPS



Type	Vce	Ic	Vcesat, Tj=25°C	Tjmax	Package
DHG50N120	1200V	50A	1.9V	150°C	TO-264

4 Electrical Characteristics

4.1 Absolute Maximum Ratings (Tc=25°C, unless otherwise noted)

Parameter		Symbol	Value	Units
Collector-to-Emitter Voltage		V_{CE}	1200	V
Gate-to-Emitter Voltage		V_{GE}	± 20	V
DC Collector current	Tc=25°C	I_C	100	A
	Tc=100°C		50	A
Pulsed Collector Current ⁽¹⁾		I_{CM}	200	A
Diode forward current	Tc=25°C	I_F	50	A
	Tc=100°C		25	
Diode Pulsed Current		I_{FM}	100	A
Short circuit withstand time, $V_{GE}=15V$, $V_{CC}=600V$, Allowed number of short circuits < 1000 Time between short circuits: $\geq 1.0s$ Tj=150°C		T_{SC}	10	μs
Power Dissipation	Tc=25°C	P_{tot}	460	W
	Tc=100°C		230	W
Junction Temperature Range		T_j	-55~150	°C
Storage Temperature Range		T_{stg}	-55~150	°C
Soldering temperature		T_L	260	°C

4.2 Thermal Characteristics

Parameter	Symbol	Rating	Units
IGBT Thermal Resistance, Junction to Case-sink	R_{thJC}	0.22	$^{\circ}C/W$
IGBT Thermal Resistance, Junction to Ambient	R_{thJA}	37.1	$^{\circ}C/W$
Diode Thermal Resistance, Junction to Case-sink	R_{thJC}	0.61	$^{\circ}C/W$

4.3 Electrical Characteristics ($T_C=25^{\circ}C$, unless otherwise noted)

Parameter	Symbol	Test Condition	Value			Units
			Min	Typ	Max	
Off Characteristics						
Collector-to-Emitter Breakdown Voltage	V_{ce}	$I_C=250\mu A, V_{GE}=0V$	1200	--	--	V
Collector-to-Emitter Leakage Current	I_{CES}	$V_{CE}=30V, V_{GE}=0V, T_C=25^{\circ}C$	--	--	1	μA
		$V_{CE}=30V, V_{GE}=0V, T_C=100^{\circ}C$	--	--	100	μA
Gate-to-Emitter Leakage Current	I_{GES}	$V_{GE}=\pm 20V, V_{CE}=0V$	--	--	± 100	nA
On Characteristics						
Gate Threshold Voltage	$V_{GE(th)}$	$V_{CE}=V_{GE}, I_C=250\mu A$	4.5	5.5	6.5	V
Collector-emitter saturation voltage	V_{cesat}	$V_{GE}=15V, I_C=50A$	--	1.9	2.2	V
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{CE}=25V, V_{GE}=0V, f=1MHz$	--	6218	--	pF
Output Capacitance	C_{oss}		--	208	--	
Reverse Transfer Capacitance	C_{rss}		--	39	--	
Switching Characteristics						
Turn-on delay time	$td(on)$	$V_{CE}=600V, I_C=50A,$ $R_g=10\Omega, V_{GE}=15V,$	--	40	--	nS
Rise time	tr		--	35	--	nS
Turn-off delay time	$td(off)$		--	340	--	nS
Fall time	tf		--	87	--	nS
Turn-on energy	E_{on}	感性负载, $T_a=25^{\circ}C$	--	1.0	--	mJ
Turn-off energy	E_{off}		--	2.3	--	mJ
Total switching energy	E_{ts}		--	3.3	--	mJ
Turn-on delay time	$td(on)$	$V_{CE}=600V, I_C=50A,$ $R_g=10\Omega, V_{GE}=15V,$	--	35	--	nS
Rise time	tr		--	37	--	nS
Turn-off delay time	$td(off)$		--	392	--	nS
Fall time	tf		--	170	--	nS
Turn-on energy	E_{on}	感性负载, $T_a=150^{\circ}C$	--	1.1	--	mJ
Turn-off energy	E_{off}		--	2.9	--	mJ
Total switching energy	E_{ts}		--	4	--	mJ
Gate charge	Q_g	$V_{CE}=600V, I_C=50A, V_{GE}=15V$	--	275	--	nC

Diode Characteristic						
Diode forward voltage	V_F	$I_F=25A$	--	3.1	--	V
Diode reverse recovery time	t_{rr}	$I_F=25A$ $di/dt=100A/uS$	--	44	--	ns
Diode peak reverse recovery current	I_{rrm}		--	2.1	--	A
Diode reverse recovery charge	Q_{rr}		--	51	--	nC

Notes:

1.Pulse duration is limited by $T_{j,max}$

6 Typical Characteristic Curves

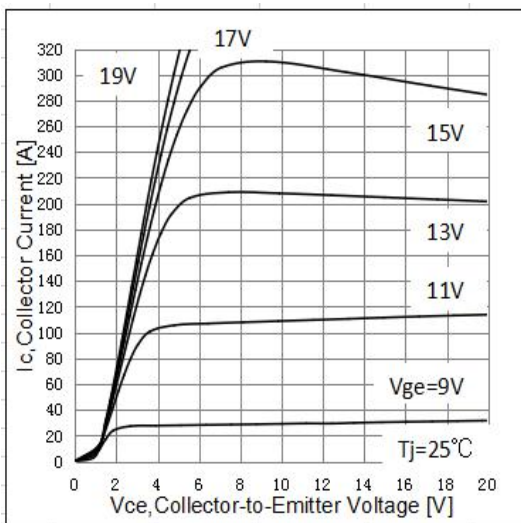


Fig1. Typical output characteristic

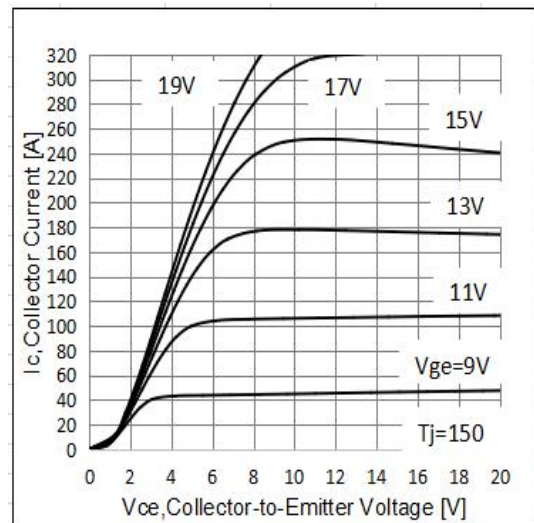


Fig2. Typical output characteristic

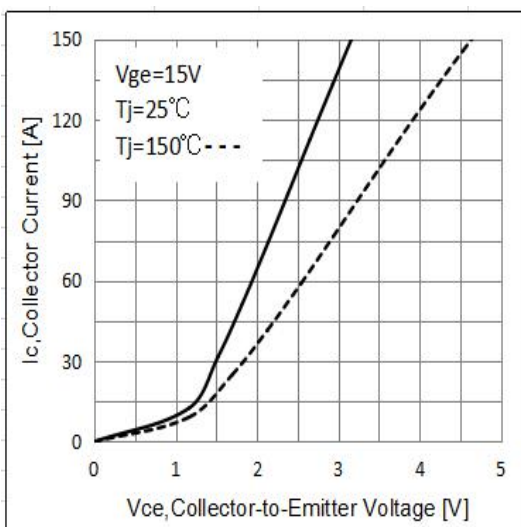


Fig3. Collector-emitter saturation voltage Characteristic

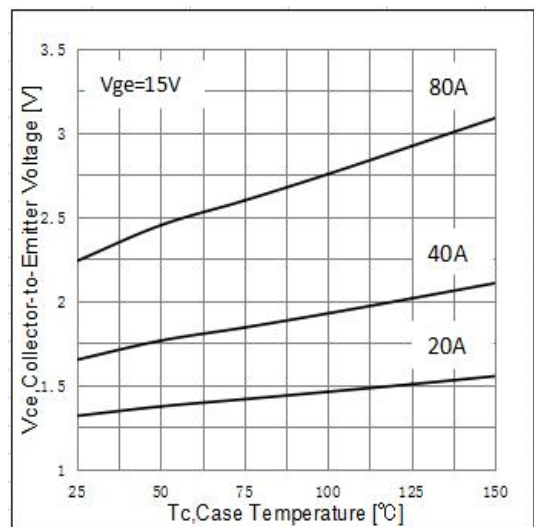


Fig4. Collector-emitter saturation voltage Temperature Characteristic

6 Typical Characteristic Curves(Continue)

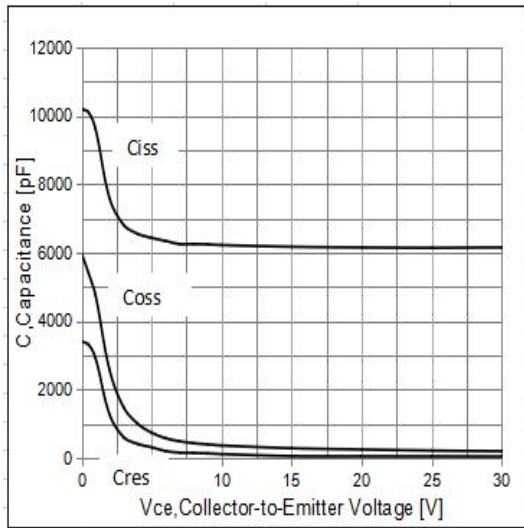


Fig5. Typical capacitance as a function of collector-emitter voltage

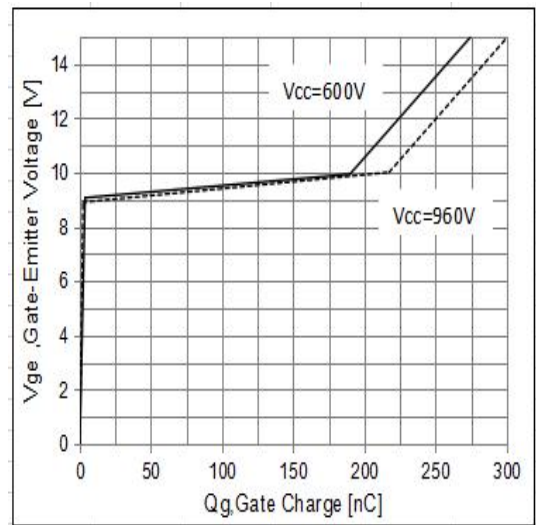


Fig6. Typical gate charge

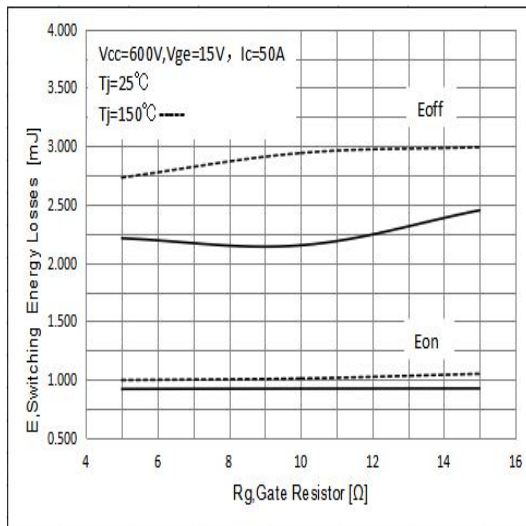


Fig7. Typical switching energy losses as a function of gate resistor

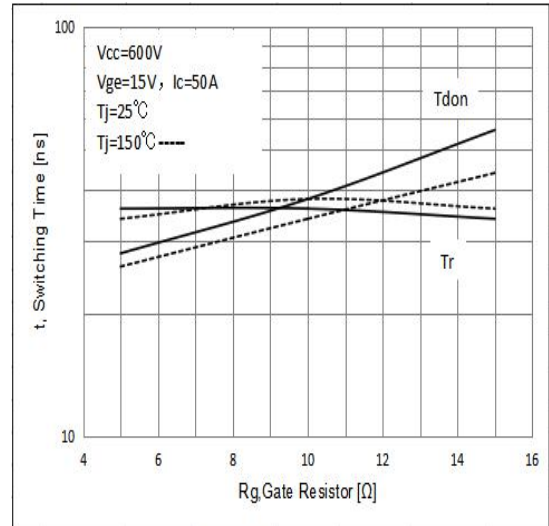


Fig8. Typical switching times as a function of gate resistor

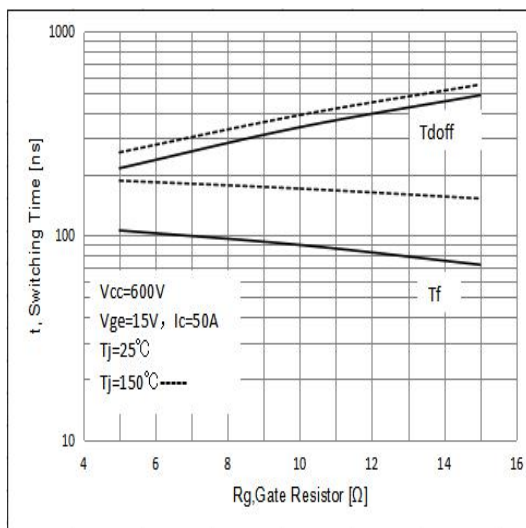


Fig9. Typical switching times as a function of gate resistor

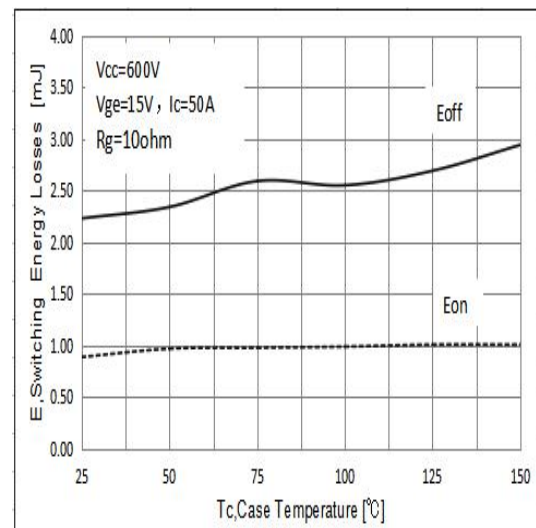


Fig10. Typical switching energy losses as a function of Case Temperature

6 Typical Characteristic Curves(Continue)

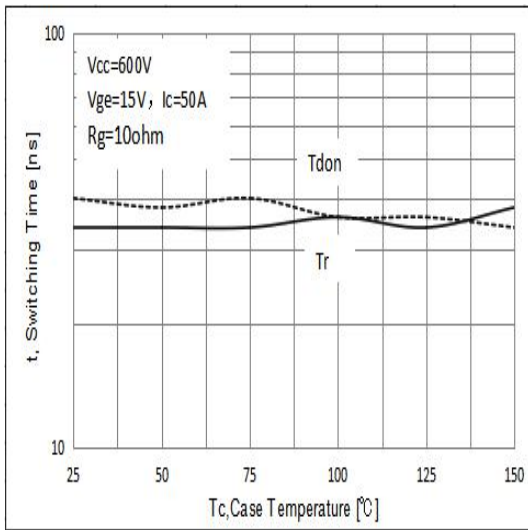


Fig11. Typical switching times as a function of Case Temperature

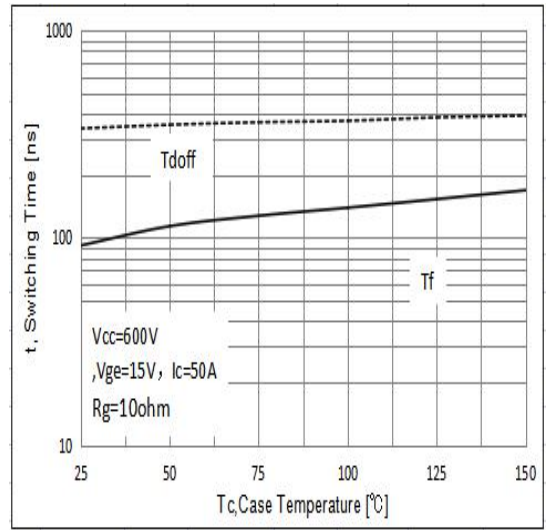


Fig12. Typical switching times as a function of Case Temperature

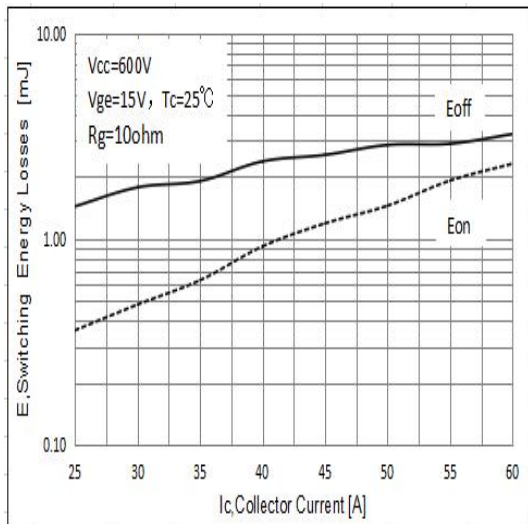


Fig13. Typical switching energy losses as a function of Collector Current

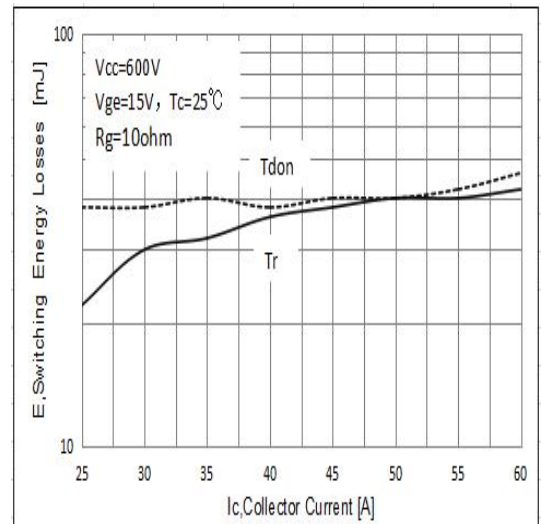


Fig14. Typical switching times as a function of Collector Current

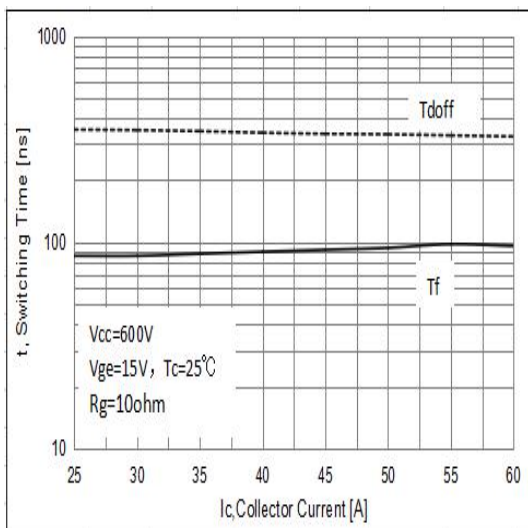


Fig15. Typical switching times as a function of Collector Current

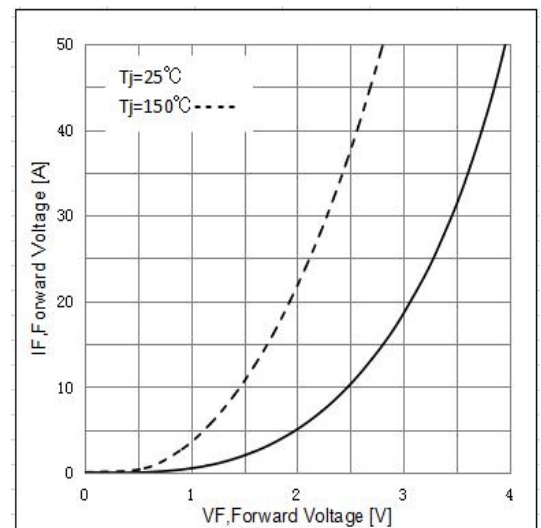


Fig16. Typical diode forward current as a function of forward voltage

6 Typical Characteristic Curves(Continue)

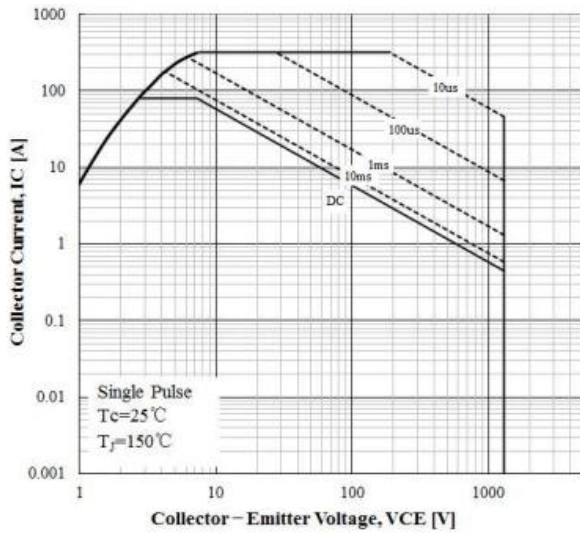


Fig17.Forward bias safe operating area

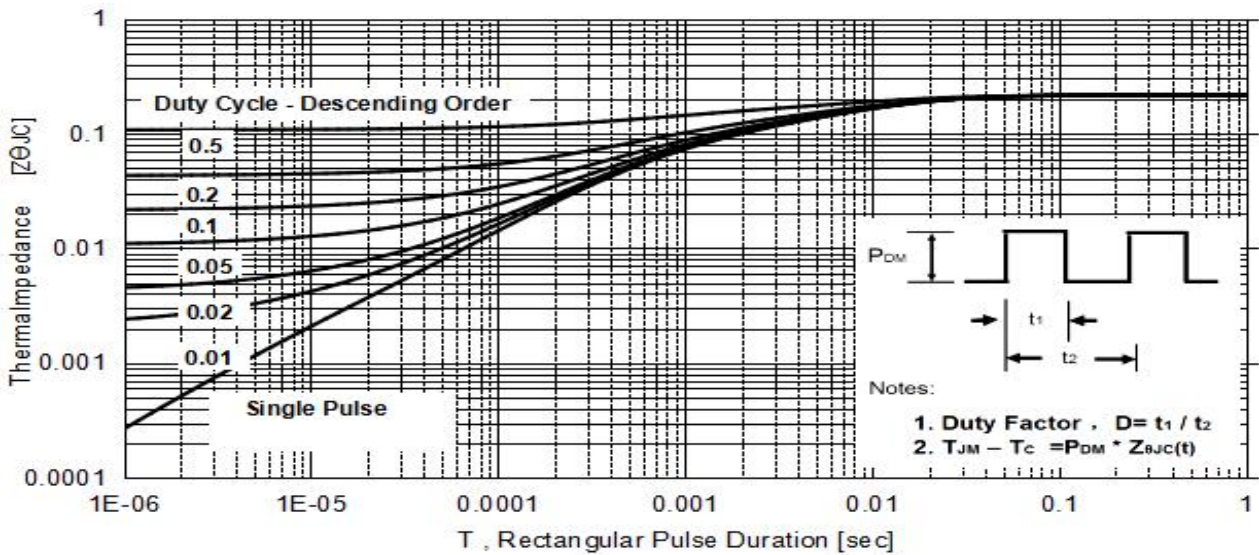


Fig18.IGBT transient thermal resistance

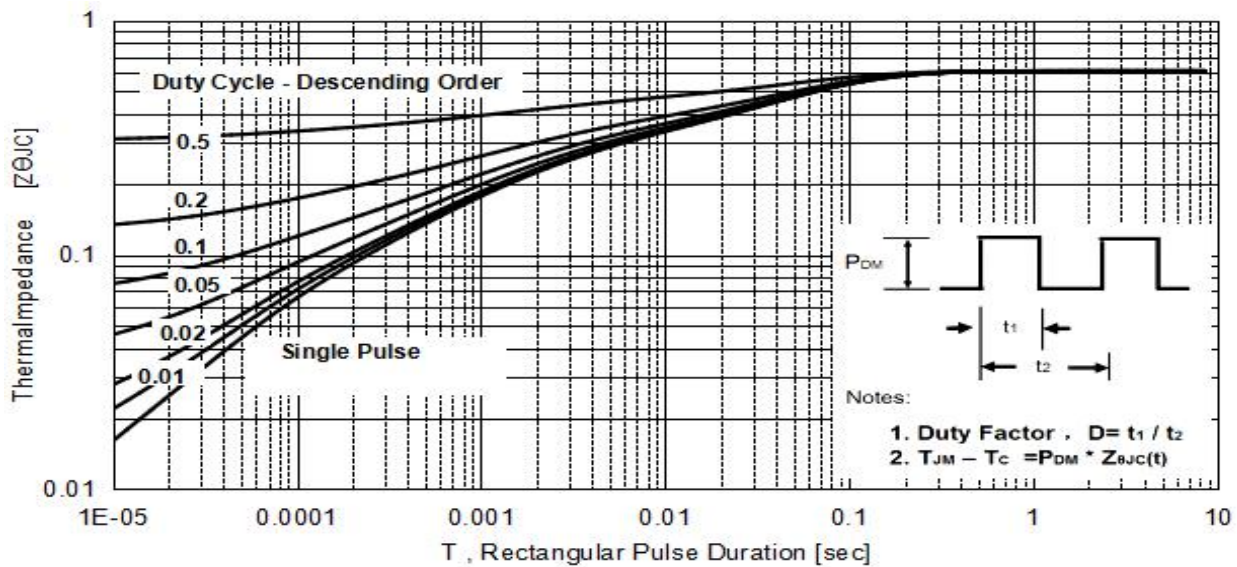
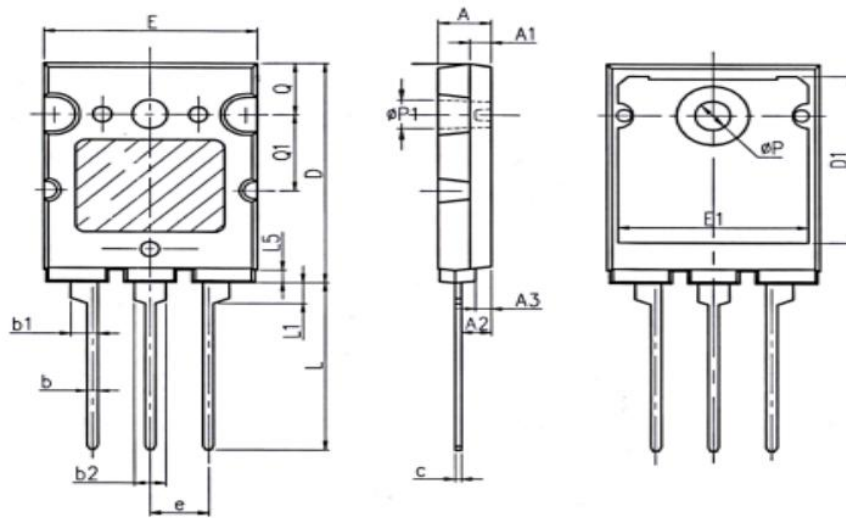


Fig19.Diode transient thermal resistance

7 Dimensions (TO-264)


SYMBOL	mm		
	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.00REF		
A2	2.50	2.80	3.10
A3	1.50REF		
b	0.90	1.00	1.25
b1	2.30	2.50	2.75
b2	2.80	3.00	3.20
c	0.50	0.60	0.85
D	25.70	26.00	26.30
D1	19.00	-	-
E	19.50	20.00	20.50
E1	16.00	-	-
e	5.45TYP		
L	19.50	20.00	20.50
L1	2.30	2.50	2.70
L5	1.35REF		
øP	3.00	3.20	3.40
øP1	3.20	3.40	3.60
Q	5.80	6.00	6.20
Q1	8.80	9.00	9.20

8 Attentions

- Jiangsu Donghai Semiconductor Technology CO.,LTD. reserves the right to change the specification without prior notice! The customer should obtain the latest version of the information before making the order and verify that the information is complete and up to date.
- It is the responsibility of the purchaser for any failure or failure of any semiconductor product under certain conditions. It is the responsibility of the purchaser to comply with safety standards and to take safety measures in the system design and machine manufacturing of Donghai products in order to avoid potential risk of failure. Injury or property damage.
- Product promotion is endless, our company will be dedicated to provide customers with better products.

9 Appendix

Revision history:

Date	REV.	Description	Page
2020.10.12	1.0	Original	